

## **Quarterly Reliability Monitoring Results**

## Quarters: Q1/2022 to Q4/2023

Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		User Part Number PMEG4015EPK-Q Part Description										
								Nexperia DHAM Schottky				
								MCD package				
		Test Conditions	Duration	# Lots	# Quantity	# Rejects						
			TEST									
			Pre- and Post-Stress									
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below						
		JESD22-A113										
		Bake Tamb = 125 °C	24 hours									
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours									
# A1	Preconditioning	Reflow soldering	3 cycles	208	9760	0						
		MIL-STD-750-1										
	HTRB	M1038 Method A										
	3	Tj = Tjmax, Vr = 100% of max. datasheet				_						
# B1	Bias	reverse voltage <sup>[1]</sup>	1000 hours	206	9320	0						
	TC	JESD22-A104										
# A4	Temperature Cycling	-65 °C to Tjmax, not to exceed 150°C	1000 cycles	53	2400	0						
		JECD22 4440										
# 42	UHAST Unbiased HAST	JESD22-A118 Tamb = 130 °C, RH = 85 %										
# A3 or	Undiased HAST	· · · · · · · · · · · · · · · · · · ·	- 96 hours	53	2400	0						
		JESD22-A102										
	AC	Tamb = 121 °C, RH = 100 %										
# A3 alt	Autoclave	Pressure = 205 kPa (29.7 psia)										
		JECD22 A101										
	H3TRB	JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of										
# A2 - It	High Humidity High	rated reverse voltage <sup>[1], [2]</sup>	1000	F2	2400	0						
# A2 alt	Temperature Reverse Bias		1000 hours	53	2400	0						
		MIL-STD-750 Method 1037										
# AF	IOL Intermittent Operating Life	ton = toff, devices powered to insure $\Delta Tj$ =	1000 have-	40	2560	0						
# A5	Intermittent Operating Life	100 °C for 15000 cycles	1000 hours	49	2560	0						
	neu	JECD22 A111										
# C0	RSH Resistance to Solder Heat	JESD22-A111	10 -									
# C8		200 -C = 3 -C	10 s	n.a.	n.a.	n.a.						
# C10	SD Coldorability	J-STD-002		27	1110	0						
# C10	Solderability	J-21D-00Z		37	1110	0						

<sup>[1]</sup> The physical limitations of Schottky diodes have to be considered (thermal runaway).

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Schottky	9320	0	0,46	2,19E+09

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<sup>[2]</sup> The maximum applied voltage is limited by test chamber set up and does not exceed 115V.